

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

MALONEY et al.

Application No. 10/027,935 Filed: December 21, 2001

For: Apparatus and Method for

Chemical-Mechanical Polishing (CMP) Head Having Direct Pneumatic Wafer Polishing

**Pressure** 

Examiner: Eley, Timothy V.

Art Unit: 3724

Confirmation No.: 2631

Palo Alto, California

Certificate of Mailing

I hereby certify that this correspondence is being deposited with sufficient postage in the United States Mail in an envelope addressed to Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on September 2004.

Leslie Hoffmann

## RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

This is a Response to the Notice of Non-Compliant Amendment mailed on August 16, 2004, a copy of which is enclosed herewith. A response is due on September 16, 2004, making this a timely response. A presentation of all of the claims, including the text of the claims follows.

While Applicants believe that no further fees are due at this time, the Commissioner is authorized to charge any fees that may due as a result of filing this amendment, including additional claims fees, including additional claims fees not already paid for, or other fees that have not been separately paid, to Deposit Account 50-2319 [Order No. A-68359-1/RMA (469113-41)].

Amendments to the Claims begins on page 2 of this paper.

Remarks begin on page 9 of this paper.

10/12/2004 RSWITH 00000002 502319 10027935

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